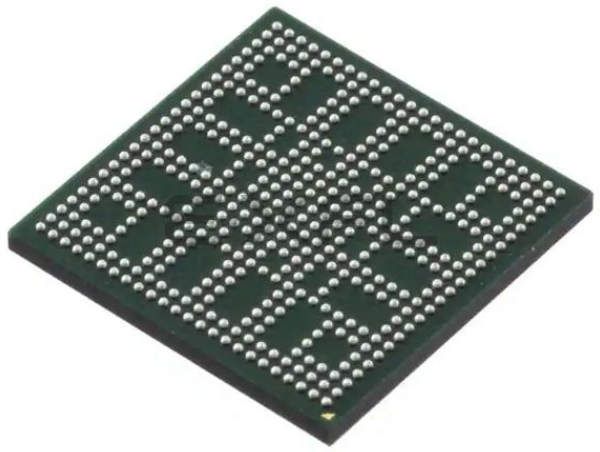

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Understanding Embedded - Microprocessors

Embedded microprocessors are specialized computing chips designed to perform specific tasks within an embedded system. Unlike general-purpose microprocessors found in personal computers, embedded microprocessors are tailored for dedicated functions within larger systems, offering optimized performance, efficiency, and reliability. These microprocessors are integral to the operation of countless electronic devices, providing the computational power necessary for controlling processes, handling data, and managing communications.

Applications of Embedded - Microprocessors

Embedded microprocessors are utilized across a broad spectrum of applications, making them indispensable in

Details	
Product Status	Active
Core Processor	ARM® Cortex®-A9
Number of Cores/Bus Width	1 Core, 32-Bit
Speed	1.0GHz
Co-Processors/DSP	Multimedia; NEON™ SIMD
RAM Controllers	LPDDR2, LVDDR3, DDR3
Graphics Acceleration	Yes
Display & Interface Controllers	Keypad, LCD
Ethernet	10/100Mbps (1)
SATA	-
USB	USB 2.0 + PHY (3)
Voltage - I/O	1.2V, 1.8V, 3.0V
Operating Temperature	0°C ~ 95°C (TJ)
Security Features	ARM TZ, Boot Security, Cryptography, RTIC, Secure Fusebox, Secure JTAG, Secure Memory, Secure RTC, Tamper Detection
Package / Case	432-TFBGA
Supplier Device Package	432-MAPBGA (13x13)
Purchase URL	https://www.e-xfl.com/product-detail/nxp-semiconductors/mcimx6l8dvn10acr

  - One of the five UARTs (UART1) supports 8-wire while others four supports 4-wire. This is due to the SoC IOMUX limitation, since all UART IPs are identical.
- Four eCSPI (Enhanced CSPI)
- Three I^2C, supporting 400 kbps
- Ethernet Controller, 10/100 Mbps
- Four Pulse Width Modulators (PWM)
- System JTAG Controller (SJC)
- GPIO with interrupt capabilities
- 8x8 Key Pad Port (KPP)
- Sony Philips Digital Interface (SPDIF), Rx and Tx
- Two Watchdog timers (WDOG)
- Audio MUX (AUDMUX)

The i.MX 6SoloLite processor integrates advanced power management unit and controllers:

- Provide PMU, including LDO supplies, for on-chip resources
- Use Temperature Sensor for monitoring the die temperature
- Support DVFS techniques for low power modes
- Use Software State Retention and Power Gating for ARM and MPE
- Support various levels of system power modes
- Use flexible clock gating control scheme

The i.MX 6SoloLite processor uses dedicated hardware accelerators to meet the targeted multimedia performance. The use of hardware accelerators is a key factor in obtaining high performance at low power consumption numbers, while having the CPU core relatively free for performing other tasks.

The i.MX 6SoloLite processor incorporates the following hardware accelerators:

- GPU2Dv2—2D Graphics Processing Unit (BitBlt).
- GPUVG—OpenVG 1.1 Graphics Processing Unit.
- PXP—PiXel Processing Pipeline. Off loading key pixel processing operations are required to support the EPD display applications.

Security functions are enabled and accelerated by the following hardware:

- ARM TrustZone including the TZ architecture (separation of interrupts, memory mapping, and so on.)
- SJC—System JTAG Controller. Protecting JTAG from debug port attacks by regulating or blocking the access to the system debug features.
- SNVS—Secure Non-Volatile Storage, including Secure Real Time Clock.
- CSU—Central Security Unit. Enhancement for the IC Identification Module (IIM). Will be configured during boot and by eFUSEs and will determine the security level operation mode as well as the TZ policy.
- A-HAB—Advanced High Assurance Boot—HABv4 with the new embedded enhancements: SHA-256, 2048-bit RSA key, version control mechanism, warm boot, CSU, and TZ initialization.

2 Architectural Overview

The following subsections provide an architectural overview of the i.MX 6SoloLite processor system.

2.1 Block Diagram

Figure 2 shows the functional modules in the i.MX 6SoloLite processor system.

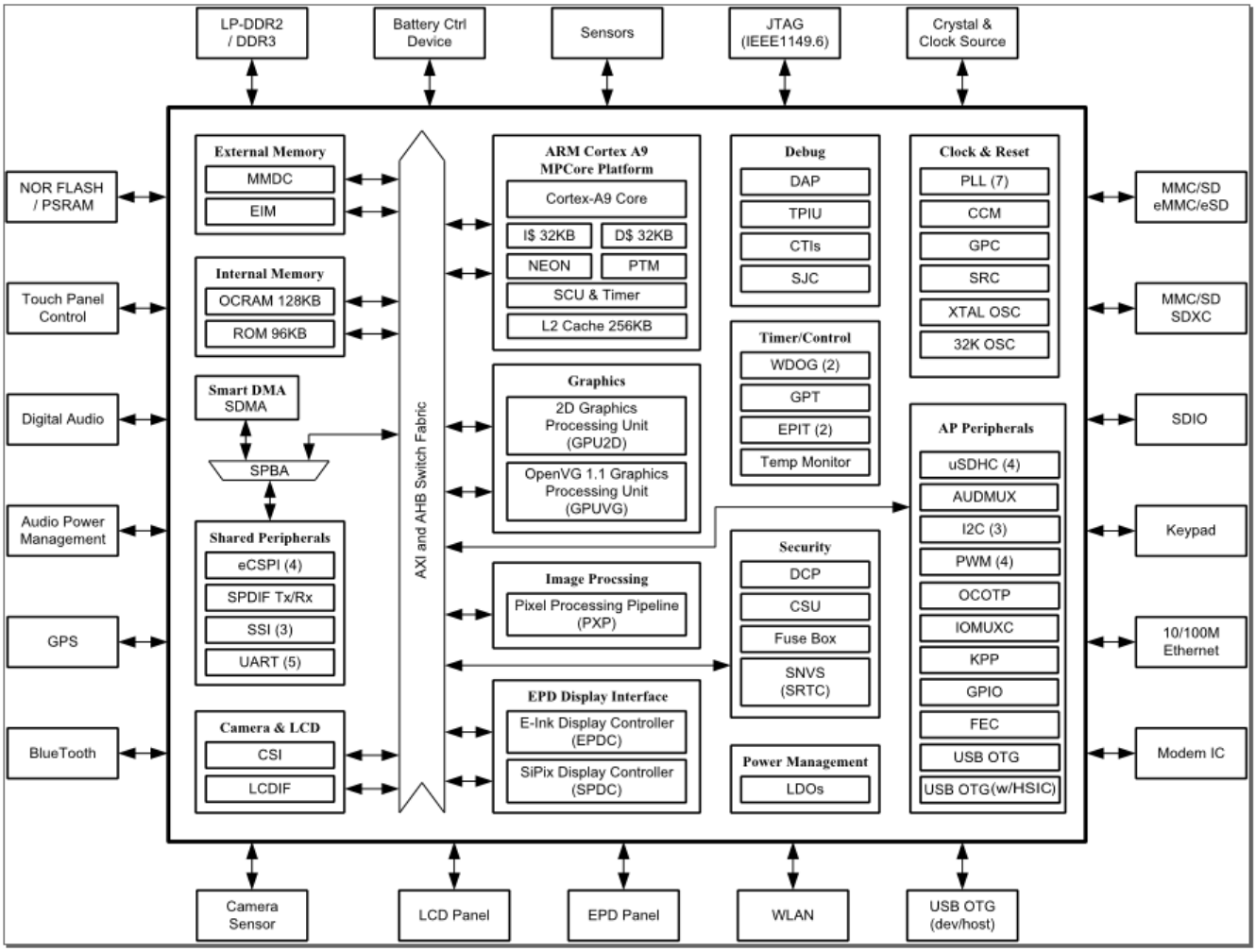

Figure 2. i.MX 6SoloLite System Block Diagram

NOTE

The numbers in brackets indicate number of module instances. For example, PWM (4) indicates four separate PWM peripherals.

Table 2. i.MX 6SoloLite Modules List (continued)

Block Mnemonic	Block Name	Subsystem	Brief Description
PXP	PiXel Processing Pipeline	Display Peripherals	A high-performance pixel processor capable of 1 pixel/clock performance for combined operations, such as color-space conversion, alpha blending, gamma-mapping, and rotation. The PXP isenhanced with features specifically for gray scale applications. In addition, the PXP supports traditional pixel/frame processing paths for still-image and video processing applications, allowing it to interface with either of the integrated EPD controllers.
RAM 128 KB	Internal RAM	Internal Memory	Internal RAM, which is accessed through OCRAM memory controller.
RNGB	Random Number Generator	Security	Random number generating module.
ROM 96KB	Boot ROM	Internal Memory	Supports secure and regular Boot Modes. Includes read protection on 4K region for content protection.
ROMCP	ROM Controller with Patch	Data Path	ROM Controller with ROM Patch support.
SDMA	Smart Direct Memory Access	System Control Peripherals	The SDMA is multi-channel flexible DMA engine. It helps in maximizing system performance by off-loading the various cores in dynamic data routing. It has the following features: • Powered by a 16-bit Instruction-Set micro-RISC engine • Multi-channel DMA supporting up to 32 time-division multiplexed DMA channels • 48 events with total flexibility to trigger any combination of channels • Memory accesses including linear, FIFO, and 2D addressing • Shared peripherals between ARM and SDMA • Very fast Context-Software switching with 2-level priority based preemptive multi-tasking • DMA units with auto-flush and prefetch capability • Flexible address management for DMA transfers (increment, decrement, and no address changes on source and destination address) • DMA ports can handle unit-directional and bi-directional flows (copy mode) • Up to 8-word buffer for configurable burst transfers • Support of byte-swapping and CRC calculations • Library of Scripts and API is available
SJC	System JTAG Controller	System Control Peripherals	The SJC provides JTAG interface, which complies with JTAG TAP standards, to internal logic. The i.MX 6SoloLite processor uses JTAG port for production, testing, and system debugging. In addition, the SJC provides BSR (Boundary Scan Register) standard support, which complies with IEEE1149.1 and IEEE1149.6 standards. The JTAG port must be accessible during platform initial laboratory bring-up, for manufacturing tests and troubleshooting, as well as for software debugging by authorized entities. The i.MX 6SoloLite SJC incorporates three security modes for protecting against unauthorized accesses. Modes are selected through eFUSE configuration.
SNVS	Secure Non-Volatile Storage	Security	Secure Non-Volatile Storage, including Secure Real Time Clock, Security State Machine, Master Key Control, and Violation/Tamper Detection and reporting.
SPDIF	Sony Phillips Digital Interface	Multimedia Peripherals	A standard audio file transfer format, developed jointly by the Sony and Phillips corporations. Has Transmitter and Receiver functionality.

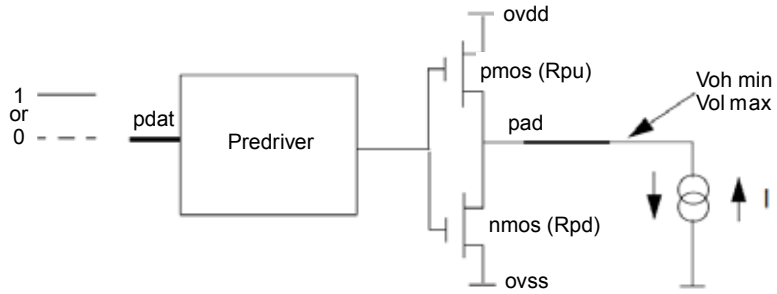

Figure 4. Circuit for Parameters Voh and Vol for I/O Cells

4.6.1 XTALI and RTC_XTALI (Clock Inputs) DC Parameters

Table 20 shows the DC parameters for the clock inputs.

Table 20. XTALI and RTC_XTALI DC Parameters

Parameter	Symbol	Test Conditions	Min	Typ	Max	Unit
XTALI high-level DC input voltage	Vih	—	0.8 x NVCC_PLL_OUT	—	NVCC_PLL_ OUT	V
XTALI low-level DC input voltage	Vil	—	0	—	0.2V	V
RTC_XTALI high-level DC input voltage	Vih	—	0.8	—	1.1[1]	V
RTC_XTALI low-level DC input voltage	Vil	—	0	—	0.2V	V
Input capacitance	C_{IN}	Simulated data	—	5	—	pF
XTALI input leakage at startup	$I_{XTALI\_STARTUP}$	Power-on startup for 0.15 msec with a driven 24 MHz RTC clock @1.1 V. [2]	—	—	600	µA
DC input current	I_{XTALI_DC}	—	—	—	2.5	µA

[1] This voltage specification must not be exceeded and, as such, is an absolute maximum specification.

[2] This current draw is present even if an external clock source directly drives XTALI.

NOTE

The Vil and Vih specifications only apply when an external clock source is used. If a crystal is used, Vil and Vih do not apply.

4.6.2 Dual Voltage General Purpose IO Cell Set (DVGPIO) DC Parameters

Table 21 shows DC parameters for GPIO pads. The parameters in Table 21 are guaranteed per the operating ranges in Table 9, unless otherwise noted.

Table 23. DDR3 I/O DC Electrical Parameters[1] (continued)

Parameters	Symbol	Test Conditions	Min	Max	Unit
Input current (no pull-up/down)	Iin	Vin = 0 or OVDD	-2.9	2.9	μA
Pull-up/pull-down impedance mismatch	MMpupd	—	-10	10	%
240 Ω unit calibration resolution	Rres	—	—	10	Ω
Keeper circuit resistance[5]	Rkeep	—	105	175	kΩ

1 Note that the JEDEC DDR3 specification (JESD79_3D) supersedes any specification in this document.

2 OVDD – I/O power supply (1.425 V – 1.575 V for DDR3

3 Vref – DDR3 external reference voltage

4 The single-ended signals need to be within the respective limits (Vih(dc) max, Vil(dc) min) for single-ended signals as well as the limitations for overshoot and undershoot (see Table 27).

5 Use an off-chip pull resistor of 10 kΩ or less to override this keeper.

4.7 I/O AC Parameters

This section includes the AC parameters of the following I/O types:

- General Purpose I/O (GPIO)
- Dual Voltage General Purpose I/O (DVGPIO)
- Double Data Rate I/O (DDR) for LPDDR2 and DDR3 modes

The GPIO and DDR I/O load circuit and output transition time waveforms are shown in Figure 5 and Figure 6.

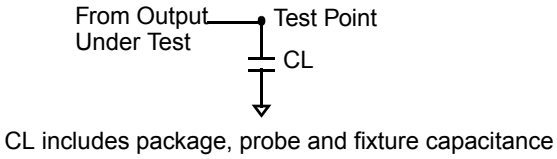

Figure 5. Load Circuit for Output

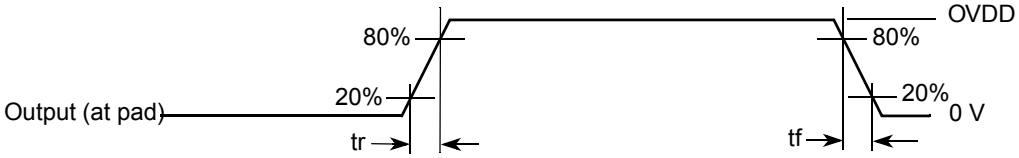

Figure 6. Output Transition Time Waveform

4.7.2 DDR I/O AC Parameters

Table 26 shows the AC parameters for DDR I/O operating in LPDDR2 mode. For details on supported DDR memory configurations, see Section 4.9.4, "Multi-Mode DDR Controller (MMDC)".

Table 26. DDR I/O LPDDR2 Mode AC Parameters[1]

Parameter	Symbol	Test Condition	Min	Typ	Max	Unit
AC input logic high	Vih(ac)	—	Vref + 0.22	—	OVDD	V
AC input logic low	Vil(ac)	—	0	—	Vref – 0.22	V
AC differential input high voltage[2]	Vidh(ac)	—	0.44	—	—	V
AC differential input low voltage	Vidl(ac)	—	—	—	0.44	V
Input AC differential cross point voltage[3]	Vix(ac)	Relative to Vref	-0.12	—	0.12	V
Over/undershoot peak	Vpeak	—	—	—	0.35	V
Over/undershoot area (above OVDD or below OVSS)	Varea	400 MHz	—	—	0.3	V-ns
Single output slew rate, measured between Vol (ac) and Voh (ac)	tsr	50 Ω to Vref. 5 pF load. Drive impedance = 4 0 Ω ±30%	1.5	—	3.5	V/ns
		50 Ω to Vref. 5pF load. Drive impedance = 60 Ω ±30%	1	—	2.5	
Skew between pad rise/fall asymmetry + skew caused by SSN	t_{SKD}	clk = 400 MHz	—	—	0.1	ns

1 Note that the JEDEC LPDDR2 specification (JESD209_2B) supersedes any specification in this document.

2 Vid(ac) specifies the input differential voltage |Vtr – Vcp| required for switching, where Vtr is the "true" input signal and Vcp is the "complementary" input signal. The Minimum value is equal to Vih(ac) – Vil(ac).

3 The typical value of Vix(ac) is expected to be about 0.5 × OVDD. and Vix(ac) is expected to track variation of OVDD. Vix(ac) indicates the voltage at which differential input signal must cross.

Table 27 shows the AC parameters for DDR I/O operating in DDR3 mode.

Table 27. DDR I/O DDR3 Mode AC Parameters[1]

Parameter	Symbol	Test Condition	Min	Typ	Max	Unit
AC input logic high	Vih(ac)	—	Vref + 0.175	—	OVDD	V
AC input logic low	Vil(ac)	—	0	—	Vref – 0.175	V
AC differential input voltage[2]	Vid(ac)	—	0.35	—	—	V
Input AC differential cross point voltage[3]	Vix(ac)	Relative to Vref	Vref – 0.15	—	Vref + 0.15	V
Over/undershoot peak	Vpeak	—	—	—	0.4	V
Over/undershoot area (above OVDD or below OVSS)	Varea	400 MHz	—	—	0.5	V-ns

Table 27. DDR I/O DDR3 Mode AC Parameters[1] (continued)

Parameter	Symbol	Test Condition	Min	Typ	Max	Unit
Single output slew rate, measured between Vol (ac) and Voh (ac)	tsr	Driver impedance = 34 Ω	2.5	—	5	V/ns
Skew between pad rise/fall asymmetry + skew caused by SSN	t_{SKD}	clk = 400 MHz	—	—	0.1	ns

1 Note that the JEDEC JESD79_3C specification supersedes any specification in this document.

2 Vid(ac) specifies the input differential voltage |Vtr-Vcp| required for switching, where Vtr is the “true” input signal and Vcp is the “complementary” input signal. The Minimum value is equal to Vih(ac) – Vil(ac).

3 The typical value of Vix(ac) is expected to be about 0.5 × OVDD. and Vix(ac) is expected to track variation of OVDD. Vix(ac) indicates the voltage at which differential input signal must cross.

4.8 Output Buffer Impedance Parameters

This section defines the I/O impedance parameters of the i.MX 6SoloLite processor for the following I/O types:

- Dual Voltage General Purpose I/O cell set (DVGPIO)
- Double Data Rate I/O (DDR) for LPDDR2, and DDR3 modes

NOTE

GPIO and DDR I/O output driver impedance is measured with “long” transmission line of impedance Ztl attached to I/O pad and incident wave launched into transmission line. Rpu/Rpd and Ztl form a voltage divider that defines specific voltage of incident wave relative to OVDD. Output driver impedance is calculated from this voltage divider (see Figure 7).

4.9.1 Reset Timings Parameters

Figure 8 shows the reset timing and Table 31 lists the timing parameters.

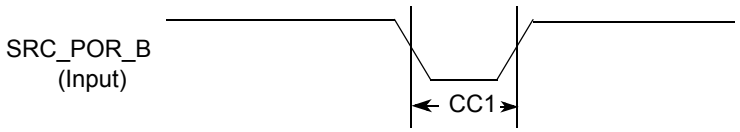

Figure 8. Reset Timing Diagram

Table 31. Reset Timing Parameters

ID	Parameter	Min	Max	Unit
CC1	Duration of POR_B to be qualified as valid.	1	—	XTALOSC_RTC_XTALI

4.9.2 WDOG Reset Timing Parameters

Figure 9 shows the WDOG reset timing and Table 32 lists the timing parameters.

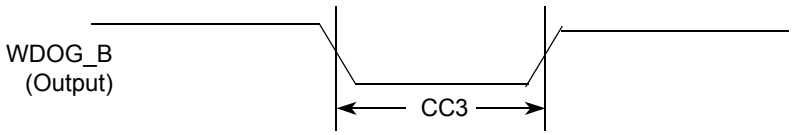

Figure 9. WDOG_B Timing Diagram

Table 32. WDOG_B Timing Parameters

ID	Parameter	Min	Max	Unit
CC3	Duration of WDOG_B Assertion	1	—	RTC_XTALI cycle

NOTE

RTC_XTALI is approximately 32 kHz. RTC_XTALI cycle is one period or approximately 30 µs.

NOTE

WDOG_B output signals (for each one of the Watchdog modules) do not have dedicated bins, but are muxed out through the IOMUX. See the IOMUX manual for detailed information.

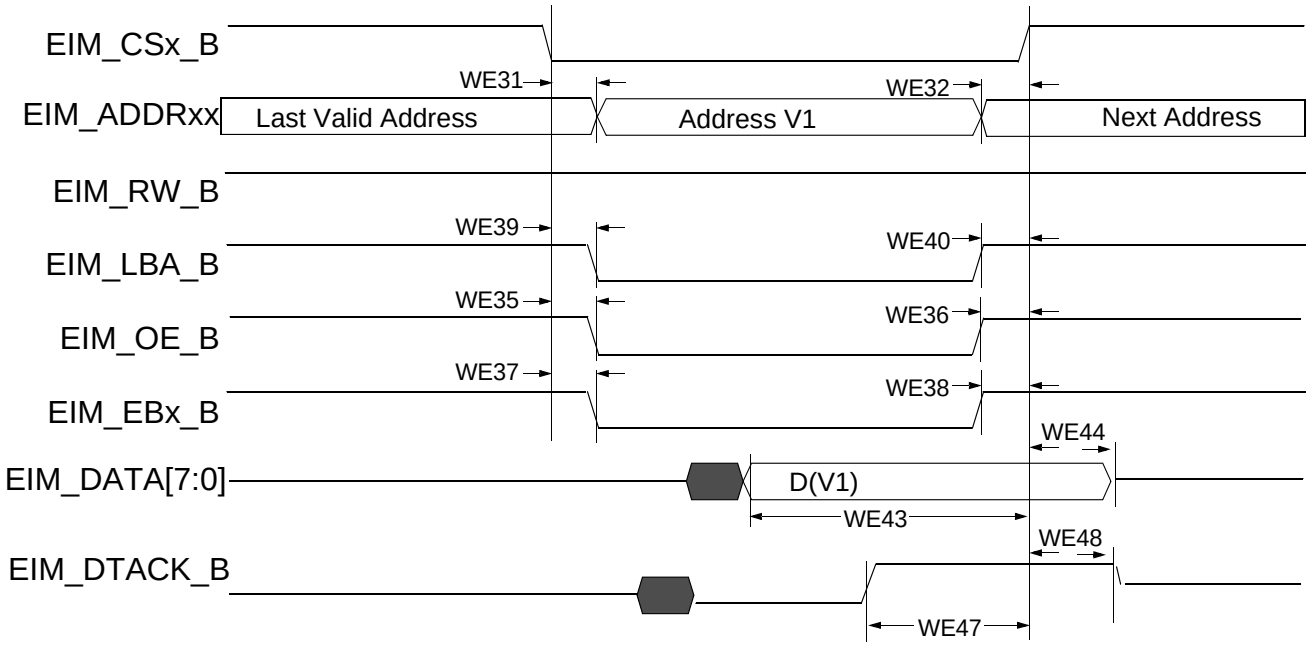

Figure 20. DTACK Read Access (DAP=0)

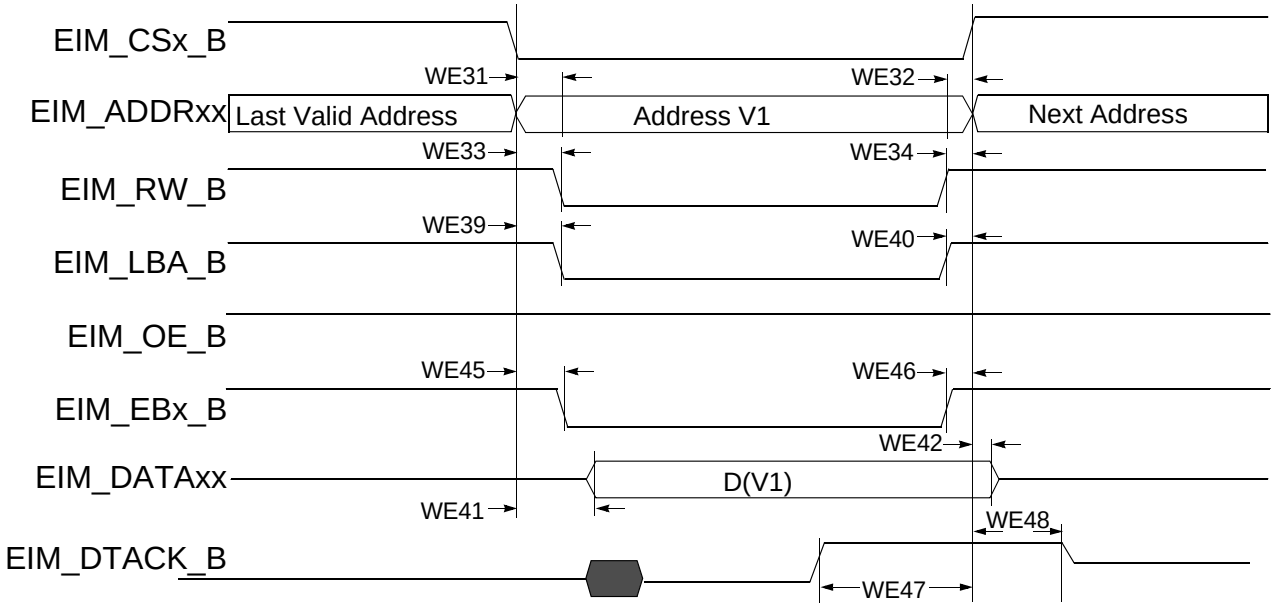

Figure 21. DTACK Write Access (DAP=0)

Table 35. EIM Asynchronous Timing Parameters Table Relative Chip Select

Reference Number	Parameter	Determination by Synchronous measured parameters[1]	Min	Max	Unit
WE31	EIM_CSx_B valid to Address Valid	WE4-WE6-CSA×t[2]	-3.5-CSA×t	3.5-CSA×t	ns
WE32	Address Invalid to EIM_CSx_B Invalid	WE7-WE5-CSN×t[3]	-3.5-CSN×t	3.5-CSN×t	ns
WE32A (muxed A/D)	EIM_CSx_B valid to Address Invalid	t[4]+WE4-WE7+(ADVN+ADVA+1-CSA[2,5,6])×t	t - 3.5 + (ADVN + ADVA + 1 - CSA)×t	t + 3.5 + (ADVN + ADVA + 1 - CSA)×t	ns
WE33	EIM_CSx_B Valid to EIM_RW_WE_B Valid	WE8-WE6+(WEA-WCSA)×t	-3.5+(WEA-WCSA)×t	3.5+(WEA-CSA)×t	ns
WE34	EIM_WE_B Invalid to EIM_CSx_B Invalid	WE7-WE9+(WEN-WCSN)×t	-3.5+(WEN-WCSN)×t	3.5-(WEN-WCSN)×t	ns
WE35	EIM_CSx_B Valid to EIM_OE_B Valid	WE10-WE6+(OEA-RCSA)×t	-3.5+(OEA-RCSA)×t	3.5+(OEA-RCSA)×t	ns
WE35A (muxed A/D)	EIM_CSx_B Valid to EIM_OE_B Valid	WE10-WE6+(OEA+RADVN+RADVA+ADH+1-RCSA)×t	-3.5 + (OEA + RADVN+RADVA+ADH+1-RCSA)×t	3.5+(OEA+RADVN+RADVA+ADH+1-RCSA)×t	ns
WE36	EIM_OE_B Invalid to EIM_CSx_B Invalid	WE7-WE11+(OEN-RCSN)×t	-3.5+(OEN-RCSN)×t	3.5+(OEN-RCSN)×t	ns
WE37	EIM_CSx_B Valid to EIM_EBx_B Valid (Read access)	WE12-WE6+(RBEA-RCSA)×t	-3.5+(RBEA- RCSA)×t	3.5+(RBEA[7]-RCSA)×t	ns
WE38	EIM_EBx_B Invalid to EIM_CSx_B Invalid (Read access)	WE7-WE13+(RBEN-RCSN)×t	-3.5+(RBEN-RCSN)×t	3.5+(RBEN-RCSN)×t	ns
WE39	EIM_CSx_B Valid to EIM_LBA_B Valid	WE14-WE6+(ADVA-CSA)×t	-3.5+(ADVA-CSA)×t	3.5+(ADVA-CSA)×t	ns
WE40	EIM_LBA_B Invalid to EIM_CSx_B Invalid (ADVL is asserted)	WE7-WE15-CSN×t	-3.5-CSN×t	3.5-CSN×t	ns
WE40A (muxed A/D)	EIM_CSx_B Valid to EIM_LBA_B Invalid	WE14-WE6+(ADVN+ADVA+1-CSA)×t	-3.5+(ADVN+ADVA+1-CSA)×t	3.5+(ADVN+ADVA+1-CSA)×t	ns
WE41	EIM_CSx_B Valid to Output Data Valid	WE16-WE6-WCSA×t	-3.5-WCSA×t	3.5-WCSA×t	ns
WE41A (muxed A/D)	EIM_CSx_B Valid to Output Data Valid	WE16-WE6+(WADVN+WADVA+ADH+1-WCSA)×t	-3.5+(WADVN+WADVA+ADH+1-WCSA)×t	3.5+(WADVN+WADVA+ADH+1-WCSA)×t	ns
WE42	Output Data Invalid to EIM_CSx_B Invalid	WE17-WE7-CSN×t	-3.5-CSN×t	3.5-CSN×t	ns

Table 35. EIM Asynchronous Timing Parameters Table Relative Chip Select (continued)

Reference Number	Parameter	Determination by Synchronous measured parameters[1]	Min	Max	Unit
MAXCO	Output maximum delay from internal driving EIM_ADDRxx/control flip-flops to chip outputs.	10	—	10	ns
MAXCSO	Output maximum delay from internal chip selects driving flip-flops to EIM_CSx_B out.	10	—	10	ns
MAXDI	EIM_DATAxx MAXIMUM delay from chip input data to its internal flip-flop	5	—	5	ns
WE43	Input Data Valid to EIM_CSx_B Invalid	MAXCO-MAXCSO+MAXDI	MAXCO-MAXCSO+MAXDI	—	ns
WE44	EIM_CSx_B Invalid to Input Data Invalid	0	0	—	ns
WE45	EIM_CSx_B Valid to EIM_EBx_B Valid (Write access)	WE12-WE6+(WBEA-WCSA)×t	-3.5+(WBEA-WCSA)×t	3.5+(WBEA-WCSA)×t	ns
WE46	EIM_EBx_B Invalid to EIM_CSx_B Invalid (Write access)	WE7-WE13+(WBEN-WCSN)×t	-3.5+(WBEN-WCSN)×t	3.5+(WBEN-WCSN)×t	ns
MAXDTI	Maximum delay from EIM_DTACK_B input to its internal flip-flop + 2 cycles for synchronization	10	—	10	ns
WE47	EIM_DTACK_B Active to EIM_CSx_B Invalid	MAXCO-MAXCSO+MAXDTI	MAXCO-MAXCSO+MAXDTI	—	ns
WE48	EIM_CSx_B Invalid to EIM_DTACK_B invalid	0	0	—	ns

1 For more information on configuration parameters mentioned in this table, see the i.MX 6SoloLite reference manual.

2 CSA means register setting for WCSA when in write operations or RCSA when in read operations.

3 CSN means register setting for WCSN when in write operations or RCSN when in read operations.

4 t means clock period from axi_clk frequency.

5 ADVA means register setting for WADVA when in write operations or RADVA when in read operations.

6 ADVN means register setting for WADVN when in write operations or RADVN when in read operations.

7 BE Assertion. This bit field determines when BE signal is asserted during read cycles.

(VSYNC), then CSI_HSYNC (HSYNC) is asserted and holds for the entire line. The pixel clock, CSI_PIXCLK (PIXCLK), is valid as long as HSYNC is asserted.

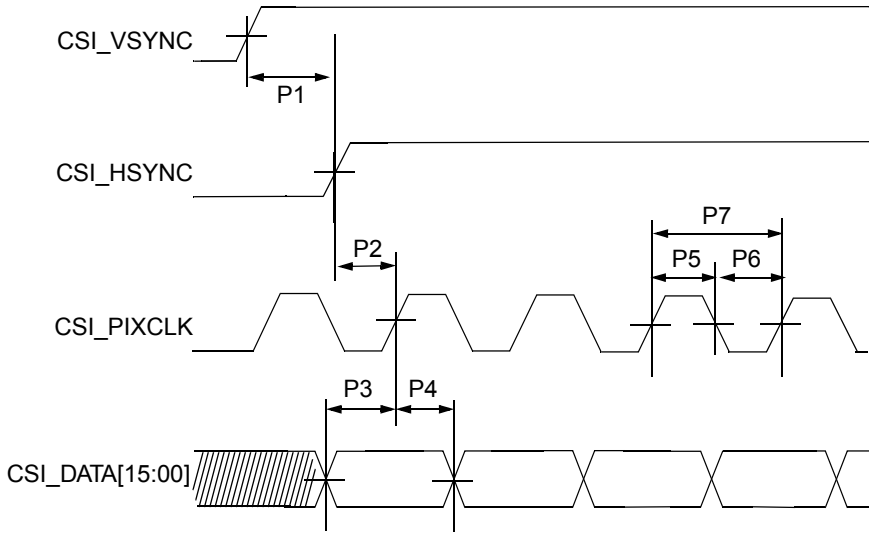

Figure 22. CSI Gated Clock Mode—Sensor Data at Falling Edge, Latch Data at Rising Edge

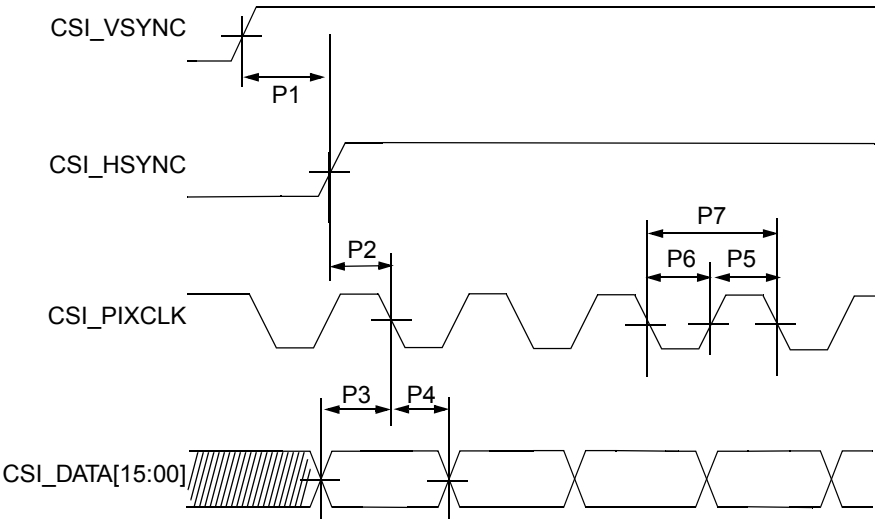

Figure 23. CSI Gated Clock Mode—Sensor Data at Rising Edge, Latch Data at Falling Edge

Table 37. CSI Gated Clock Mode Timing Parameters

ID	Parameter	Symbol	Min	Max	Units
P1	CSI_VSYNC to CSI_HSYNC time	tV2H	67.5	—	ns
P2	CSI_HSYNC setup time	tHsu	2	—	ns
P3	CSI DATA setup time	tDsu	2.5	—	ns

[5]To satisfy hold timing, the delay difference between clock input and cmd/data input must not exceed 2 ns.

4.10.4.2 eMMC4.4/4.41 (Dual Data Rate) eSDHCv3 AC Timing Parameters

Figure 28 depicts the timing of eMMC4.4/4.41. Table 42 lists the eMMC4.4/4.41 timing characteristics. Be aware that only SDx_DATAx is sampled on both edges of the clock (not applicable to SDx_CMD).

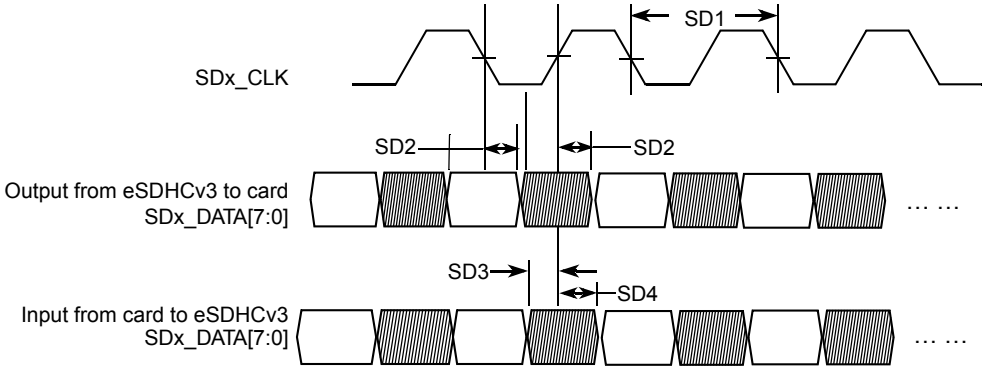

Figure 28. eMMC4.4/4.41 Timing Diagram

Table 42. eMMC4.4/4.41 Interface Timing Parameters

ID	Parameter	Symbols	Min	Max	Unit
Card Input Clock					
SD1	Clock Frequency (eMMC4.4/4.41 DDR)	f_{PP}	0	52	MHz
SD1	Clock Frequency (SD3.0 DDR)	f_{PP}	0	50	MHz
uSDHC Output / Card Inputs SD_CMD, SD_DATAx (Reference to CLK)					
SD2	uSDHC Output Delay	t_{OD}	2.5	7.1	ns
uSDHC Input / Card Outputs SD_CMD, SD_DATAx (Reference to CLK)					
SD3	uSDHC Input Setup Time	t_{ISU}	1.7	—	ns
SD4	uSDHC Input Hold Time	t_{IH}	1.5	—	ns

4.10.5 HS200 Mode Timing Parameters

Figure 30 depicts the timing of HS200 mode, and Table 44 lists the HS200 timing characteristics.

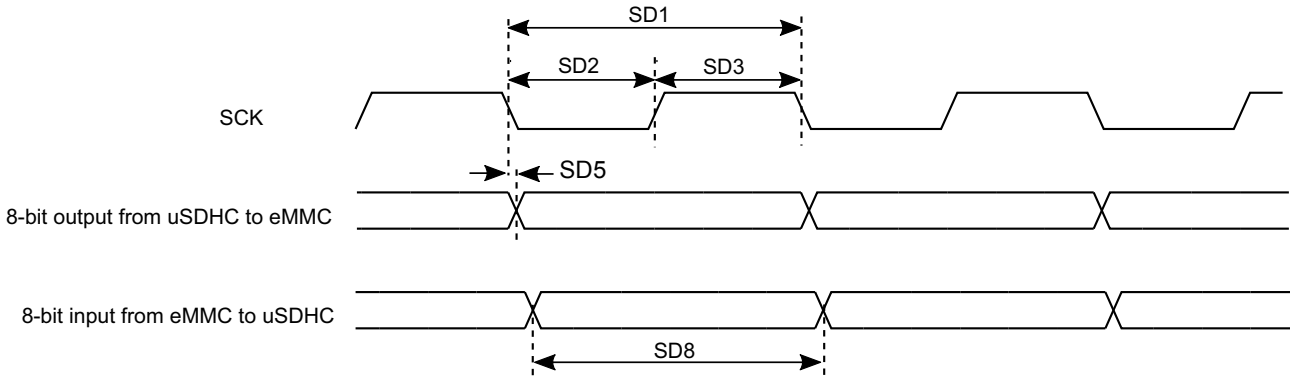

Figure 30. HS200 Mode Timing Diagram

Table 44. HS200 Interface Timing Parameters

ID	Parameter	Symbols	Min	Max	Unit
Card Input Clock					
SD1	Clock Frequency Period	t_{CLK}	5	—	ns
SD2	Clock Low Time	t_{CL}	$0.46 \times t_{CLK}$	$0.54 \times t_{CLK}$	ns
SD3	Clock High Time	t_{CH}	$0.46 \times t_{CLK}$	$0.54 \times t_{CLK}$	ns
uSDHC Output/Card Inputs SD_CMD, SDx_DATAx in HS200 (Reference to CLK)					
SD5	uSDHC Output Delay Setup Time	t_{OD}	-1.6	0.74	ns
uSDHC Input/Card Outputs SD_CMD, SDx_DATAx in HS200 (Reference to CLK)[1]					
SD8	Card Output Data Window	t_{ODW}	$0.5 \times t_{CLK}$	—	ns

1 HS200 is for 8 bits while SDR104 is for 4 bits.

4.10.6 FEC AC Timing Parameters

This section describes the electrical information of the Fast Ethernet Controller (FEC) module. The FEC is designed to support both 10 and 100 Mbps Ethernet/IEEE 802.3 networks. An external transceiver interface and transceiver function are required to complete the interface to the media. The FEC supports the 10/100 Mbps RMII (10 pins in total) and the 10 Mbps (only 7-wire interface, which uses 7 of the RMII pins), for connection to an external Ethernet transceiver. For the pin list of RMII and 7-wire, see the i.MX 6SoloLite Reference Manual.

This section describes the AC timing specifications of the FEC. The RMII signals are compatible with transceivers operating at a voltage of 3.3 V.

4.10.8 Pulse Width Modulator (PWM) Timing Parameters

This section describes the electrical information of the PWM. The PWM can be programmed to select one of three clock signals as its source frequency. The selected clock signal is passed through a prescaler before being input to the counter. The output is available at the pulse-width modulator output (PWMx_OUT) external pin (see external signals table in the i.MX 6SoloLite reference manual for PWM pin assignments).

Figure 33 depicts the timing of the PWM, and Table 47 lists the PWM timing parameters.

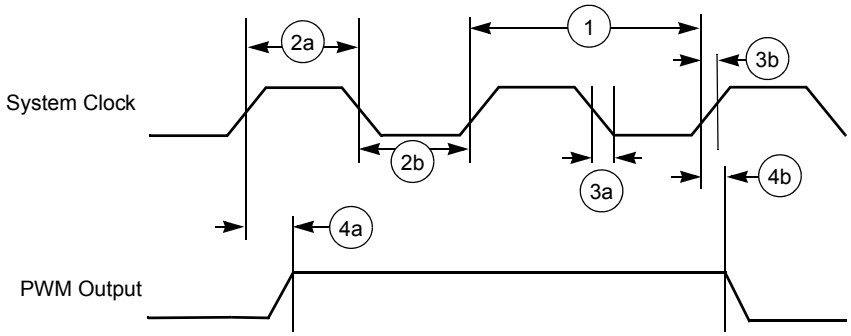

Figure 33. PWM Timing Diagram

Table 47. PWM Output Timing Parameters

Reference Number	Parameter	Min	Max	Unit
1	System CLK frequency[1]	0	ipg_clk	MHz
2a	Clock high time	12.29	—	ns
2b	Clock low time	9.91	—	ns

1 CL of PWMx_OUT = 30 pF

4.10.9 SCAN JTAG Controller (SJC) Timing Parameters

Figure 34 depicts the SJC test clock input timing. Figure 35 depicts the SJC boundary scan timing. Figure 36 depicts the SJC test access port. Signal parameters are listed in Table 48.

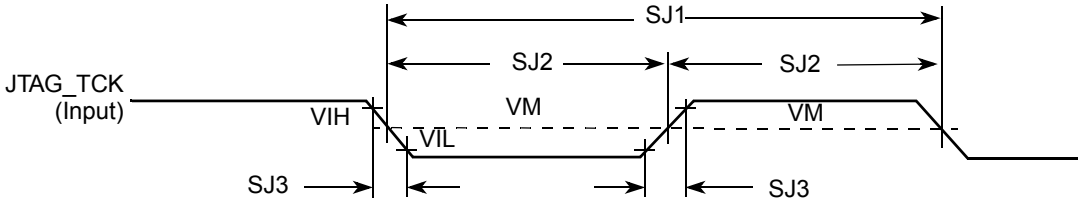

Figure 34. Test Clock Input Timing Diagram

Table 53. SSI Transmitter with External Clock Timing Parameters (continued)

ID	Parameter	Min	Max	Unit
Synchronous External Clock Operation				
SS44	AUDx_RXD setup before AUDx_TXC falling	10.0	—	ns
SS45	AUDx_RXD hold after AUDx_TXC falling	2.0	—	ns
SS46	AUDx_RXD rise/fall time	—	6.0	ns

NOTE

- All the timings for the SSI are given for a non-inverted serial clock polarity (TXC/RXC = 0) and a non-inverted frame sync (TXFS/RXFS = 0). If the polarity of the clock and/or the frame sync have been inverted, all the timing remains valid by inverting the clock signal TXC/RXC and/or the frame sync TXFS/RXFS shown in the tables and in the figures.
- All timings are on AUDMUX Pads when SSI is used for data transfer.
- The terms WL and BL refer to Word Length (WL) and Bit Length (BL).
- For internal Frame Sync operation using external clock, the FS timing is same as that of TXD (for example, during AC97 mode of operation).

4.10.11.4 SSI Receiver Timing with External Clock

Figure 43 depicts the SSI receiver external clock timing and Table 54 lists the timing parameters for the receiver timing with the external clock.

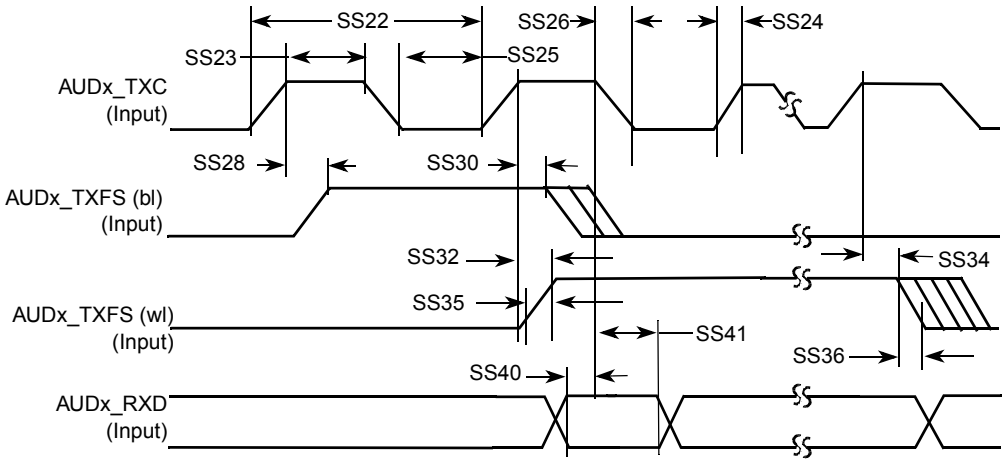

Figure 43. SSI Receiver External Clock Timing Diagram

- Battery Charging Specification (available from USB-IF)
  - Revision 1.2, December 7, 2010
  - Portable device only.

5 Boot Mode Configuration

This section provides information on boot mode configuration pins allocation and boot devices interfaces allocation.

5.1 Boot Mode Configuration Pins

Table 62 provides boot options, functionality, fuse values, and associated pins. Several input pins are also sampled at reset and can be used to override fuse values, depending on the value of BT_FUSE_SEL fuse. The boot option pins are in effect when BT_FUSE_SEL fuse is '0' (cleared, which is the case for an unblown fuse). For detailed boot mode options configured by the boot mode pins, see the i.MX 6SoloLite Fuse Map document and the System Boot chapter of the i.MX 6SoloLite reference manual.

Table 62. Fuses and Associated Pins Used for Boot

Ball Name	Direction at Reset	eFuse Name
Boot Mode Selection		
BOOT_MODE1	Input	Boot Mode Selection
BOOT_MODE0	Input	Boot Mode Selection
Boot Options[1]		
LCD_DAT0	Input	BOOT_CFG1[0]
LCD_DAT1	Input	BOOT_CFG1[1]
LCD_DAT2	Input	BOOT_CFG1[2]
LCD_DAT3	Input	BOOT_CFG1[3]
LCD_DAT4	Input	BOOT_CFG1[4]
LCD_DAT5	Input	BOOT_CFG1[5]
LCD_DAT6	Input	BOOT_CFG1[6]
LCD_DAT7	Input	BOOT_CFG1[7]
LCD_DAT8	Input	BOOT_CFG2[0]
LCD_DAT9	Input	BOOT_CFG2[1]
LCD_DAT10	Input	BOOT_CFG2[2]
LCD_DAT11	Input	BOOT_CFG2[3]
LCD_DAT12	Input	BOOT_CFG2[4]
LCD_DAT13	Input	BOOT_CFG2[5]
LCD_DAT14	Input	BOOT_CFG2[6]
LCD_DAT15	Input	BOOT_CFG2[7]
LCD_DAT16	Input	BOOT_CFG4[0]
LCD_DAT17	Input	BOOT_CFG4[1]
LCD_DAT18	Input	BOOT_CFG4[2]

Table 63. Interfaces Allocation During Boot (continued)

Interface	IP Instance	Allocated Ball Names During Boot	Comment
I2C	I2C-2	I2C2_SCL, I2C2_SDA	—
I2C	I2C-3	AUD_RXFS, AUD_RXC	—
USB	USB_OTG1_PHY	USB_OTG1_DP USB_OTG1_DN USB_OTG1_VBUS USB_OTG1_CHD_B USB_OTG1_DP USB_OTG1_DN USB_OTG1_VBUS	—

6 Package Information and Contact Assignments

This section includes the contact assignment information and mechanical package drawing.

6.1 Updated Signal Naming Convention

The signal names of the i.MX6 series of products have been standardized to better align the signal names within the family and across the documentation. Some of the benefits of these changes are as follows:

- The names are unique within the scope of an SoC and within the series of products
- Searches will return all occurrences of the named signal
- The names are consistent between i.MX 6 series products implementing the same modules
- The module instance is incorporated into the signal name

This change applies only to signal names. The original ball names have been preserved to prevent the need to change schematics, BSDL models, IBIS models, and so on.

Throughout this document, the updated signal names are used except where referenced as a ball name (such as the Functional Contact Assignments table, Ball Map table, and so on). A master list of the signal name changes is in the document, *IMX 6 Series Signal Name Mapping* (EB792). This list can be used to map the signal names used in older documentation to the new standardized naming conventions.

6.2.2 13 x 13 mm Ground, Power, Sense, Not Connected, and Reference Contact Assignments

Table 65 shows the device connection list for ground, power, sense, and reference contact signals.

Table 65. 13 x 13 mm Supplies Contact Assignment

Supply Rail Name	Ball(s) Position(s)	Remark
DRAM_VREF	N5	—
GND	A1, A4, A7, A24, C6, C10, C14, C19, D1, D2, E5, G1, G8, G9, G10, G11, G13, G14, G15, G17, G18, H3, H7, H18, H22, J5, K1, L7, L9, L10, L11, L12, L13, L14, L15, L16, M5, M7, M8, M9, M10, M11, M12, M13, M14, M15, M16, M17, N3, N7, N8, N9, N10, N11, N12, N13, N14, N15, N16, N17, N22, P9, P10, P11, P12, P13, P14, P15, P16, R1, T5, U3, U7, U18, U22, V1, V8, V9, V10, V11, V12, V13, V14, V15, V16, V18, Y5, AA1, AA2, AB10, AB14, AB18, AC18, AD1, AD4, AD7, AD24	—
GND_KELVIN	V17	Must be connected
GPANAIO	AD22	Analog output for NXP use only. This output must remain unconnected.
NVCC_1P2V	W7	—
NVCC18_IO	E14, E15, M20, Y11	—
NVCC33_IO	H10, H11, H14, H15, L18, M18, T19, U10, U11	—
NVCC_DRAM	E6, Y6, G7, H6, J6, N6, P7, T6, U6, V7	Supply of the DDR Interface
NVCC_DRAM_2P5	M6	—
NVCC_PLL	Y19	—
VDD_ARM_CAP	J15, J16, J17, J18, K15, K16, K17, K18	Secondary Supply for the ARM0 and ARM1 Cores (internal regulator output—requires capacitor if internal regulator is used)
VDD_ARM_IN	J12, J13, J14, K12, K13, K14	Primary Supply, for the ARM0 and ARM1 Core’ Regulator
VDD_HIGH_CAP	R14, R15, T14, T15	Secondary Supply for the 2.5 V domain (internal regulator output—requires capacitor if internal regulator is used)
VDD_HIGH_IN	R12, R13, T12, T13	Primary Supply for the 2.5 V Regulator
VDD_PU_CAP	R7, R8, R9, T7, T8, T9	Secondary Supply for the VPU and GPU’s (internal regulator output—requires capacitor if internal regulator is used)
VDD_PU_IN	R10, R11, T10, T11	—
VDD_SNVS_CAP	AD20	Secondary Supply for the SNVS (internal regulator output—requires capacitor if internal regulator is used)